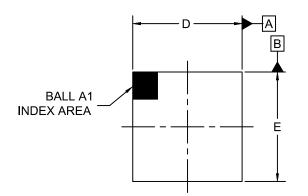


## WLCSP36 2.43x2.43x0.488

CASE 567WJ ISSUE A

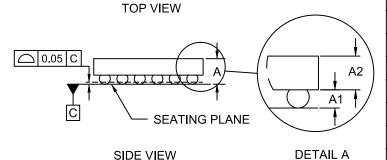
**DATE 03 OCT 2018** 



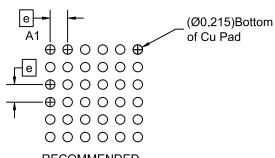
## NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

	MILLIMETERS			
DIM	MIN.	NOM.	MAX.	
Α	0.450	0.488	0.526	
A1	0.176	0.196	0.216	
A2	0.274	0.292	0.310	
b	0.240	0.260	0.280	
D	2.400	2.430	2.460	
E	2.400	2.430	2.460	
е	0.40 BSC			
х	0.200	0.215	0.230	
у	0.200	0.215	0.230	



Øb е 36X  $\oplus$   $\bigcirc$   $\bigcirc$   $\bigcirc$   $\bigcirc$ r e 0.00000Ε  $\oplus$   $\bigcirc$   $\bigcirc$   $\bigcirc$   $\bigcirc$   $\bigcirc$ D <u>⊕ ō olo ō o</u> С 000000 0000003 4 5 ·(x) **BOTTOM VIEW** 



RECOMMENDED MOUNTING FOOTPRINT (NSMD PAD TYPE)

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DESCRIPTION:	WLCSP36 2.43x2.43x0.488		PAGE 1 OF 1	

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